

## AMAZON RESEARCH AWARDS: GUIDANCE FOR FACULTY

For faculty who are applying for an [Amazon Research Award \(ARA\)](#), here is some UW guidance for how to proceed at the application and award stages:

### Pre-award

- The UW accepts ARA funding through Gift Services. Because of this, faculty should not complete an eGC1.
- As you build your project budget, remember to include the required institutional [gift assessment](#), while staying within the award cap.

### Post-award

- Amazon will notify you by email if you are being funded. This notification will likely include a form for you to complete and gift letter to sign. Please **do not sign** the gift letter. Gift letters must be reviewed and signed by the UW's designated signatory in University Advancement. Begin with your local grant manager and/or CFR (corporate and foundation relations) staff. They will guide you through the approval and signature process.
- Units are asked **not** to request a new gift fund for each ARA. Instead, funds should be deposited in a faculty member's existing gift fund if applicable, or in a broader-purpose unit gift fund. ARA project funds placed in broader-purpose gift funds should be managed using worktags to identify and access the funding.

### Considering the "Think Big" category?

Amazon's [current ARA call for proposals](#) encompasses five distinct opportunities: [AI for Information Security](#); [Amazon Ads](#); [AWS AI: Agentic AI](#); [Build on Trainium](#); and [Think Big](#). For faculty contemplating applying to the Think Big call, Amazon recommends you scroll down the [main page](#) to look at the earlier ARA topics for inspiration and an understanding of Amazon's interest areas. In addition to what appears in past ARA call-for-proposal topics on Amazon's website, Amazon also encourages research proposals for a full range of other scientific domains that might include (but should not be limited to):

- Additive manufacturing: 3D printing technologies and emerging applications of 3D printing
- Advanced semi-conductor packaging: Wafer-scale systems, optical inter-chip, communications, and 3D die stacking
- In-memory compute and in-storage compute
- Power-fusion, fission and alternative power
- Utility-scale energy storage or large-scale battery storage

### Questions?

- For process questions, please email Michelle Barnett in Central CFR at [mb1@uw.edu](mailto:mb1@uw.edu).
- For topic questions, please email Joanna Glickler in Central CFR at [glickler@uw.edu](mailto:glickler@uw.edu) or connect with your unit CFR staff member.